

**AMENDMENTS TO THE CLAIMS**

Please **AMEND** claims 1, 4, 5, and 8 as shown below.

This listing of claims will replace all prior versions, and listings, of claims in the application.

1. (Currently Amended) A method for manufacturing a thin flat panel display, the method comprising:

preparing an etchable upper substrate and an etchable lower substrate;

forming image display devices on an inner surface of the lower substrate in such a way that at least two image display devices are isolated from each other;

combining the upper substrate and the lower substrate together so that the image display devices are each surrounded by an inner sealant and the image display devices and the inner sealants are surrounded by an outer sealant;

etching ~~outer surfaces of~~ the upper substrate to a thickness of about 100 micrometers or less, and etching the lower substrate to a thickness of about 100 micrometers or less; and

cutting the combined upper and lower substrates in units of an image display device such that each image display device is separate,

wherein the combining comprises completely covering each lateral side of the combined upper and lower substrates with an unetchable protection film, and

wherein the image display devices are organic EL display devices.

2. (Original) The method of claim 1, wherein the upper and lower substrates are formed of a glass-based material.

3. (Canceled)

4. (Currently Amended) The method of claim 1, wherein ~~during the etching, the outer surfaces of the upper and lower substrates are etched so that~~ the upper substrate and the lower substrate are etched to each have a total thickness of at most 0.5mm.

5. (Currently Amended) A method for manufacturing a thin flat panel display, the method comprising:

preparing an etchable upper substrate and an etchable lower substrate;  
forming an image display device on an inner surface of the lower substrate;  
combining the upper substrate and the lower substrate together so that the image display device is surrounded by an inner sealant and the image display device and the inner sealant are surrounded by an outer sealant; and

etching ~~outer surfaces of~~ the upper substrate to a thickness of about 100 micrometers or less, and etching the lower substrate to a thickness of about 100 micrometers or less.

wherein the combining comprises completely covering each lateral side of the combined upper and lower substrates with an unetchable protection film, and

wherein the image display device is an organic EL display device.

6. (Original) The method of claim 5, wherein the upper substrate and the lower substrate are formed of a glass-based material.

7. (Canceled)

8. (Currently Amended) The method of claim 5, wherein ~~during the etching step, the outer surfaces of the upper substrate and the lower substrate are etched so that~~ the upper and lower substrates are etched to each have a total thickness of at most 0.5mm.

9-10. (Canceled)

11. (Previously Presented) The method of claim 1, wherein the inner sealant completely surrounds the image display device.

12. (Canceled)

13. (Previously Presented) The method of claim 5, wherein the inner sealant completely surrounds the image display device.

14. (Canceled)